

XCede® HD

SUPERIOR PERFORMANCE WITH HIGHER DENSITY

The XCede HD® connector leverages the same core technologies as standard XCede®, providing a robust solution for tighter card pitches and chassis designs where space requirements and density are critical. XCede HD achieves the highest performance in an HM compatible form factor.

- Differential pairs 28–84 per inch (11–33 differential pairs per centimeter)
- Price and performance scalability
- Modular construction with integrated power and guidance options
- Compliance with the Hard Metric form factor requirements outlined in EN 61076–4–101:2001
- 85Ω and 100Ω impedance



FEATURES

- Data rates scalable from 6Gb/s to 20Gb/s to support system upgrades without costly redesigns
- Compliance with the Hard Metric form factor requirements outlined in EN 61076–4–101:2001
- Proprietary crosstalk reducing technology
- Miniaturized compliant pins
- Leverage application specific derivatives including coplanar and orthogonal configurations
- Shield contacts mate before signal contacts providing up to a 4mm minimum wipe
- Embedded capacitor available
- Differential pairs 28–84 per inch (11–33 differential pairs per centimeter)

BENEFITS

- Gear practical performance requirements for future data rates while making a significant impact on current systems
- Highest density with 1.8mm pitch
- Excellent common mode performance with proven EMI and signal integrity advantages
- Improved impedance matching allowing for deeper backdrilling
- Complete solution for unique customer requirements
- Enables hot plugging
- Additional margin and overall system cost savings
- Meets the high density needs of today's challenging architectures

TECHNICAL INFORMATION

MATERIAL

- Contact Finish Area: Gold
- Contact Base Metal: High Performance Copper Alloy
- Housings: Glass Reinforced Polyester (LCP)

ELECTRICAL PERFORMANCE

- Signal Contact Current Rating: 1A
- Contact Resistance Change: 10mohm Maximum
- Dielectric Withstanding Voltage: 750V RMS Peak

MECHANICAL PERFORMANCE

- 2mm and 3mm Signal Wipes Available
- Housing Capture: 0.8mm X and 0.61mm Y
- Guide Capture: 2mm X and Y
- Durability: 250 Mating Cycles

ENVIRONMENTAL

- Operating Temperature Range: -40°C to 105°C

APPROVALS AND CERTIFICATIONS

- UL94-V-0

SPECIFICATIONS

- TB-2235 XCede HD General Product Specification
- TB-2237 XCede HD Routing Guidelines
- TB-2245 XCede HD and XCede HD Plus Backplane Removal and Reinsertion Process
- TB-2252 XCede HD and XCede HD Plus Backplane Installation Process
- TB-2253 XCede HD and XCede HD Plus Wafer Removal and Replacement
- TB-2272 XCede HD Connector Design Guidelines

PACKAGING

- PVC Trays (ESD)

TARGET MARKETS/APPLICATIONS



Hubs
Switches
Routers
Wireless Infrastructure



Servers
Networked Storage Systems
Supercomputers